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STPS0530Z

SCHOTTKY RECTIFIERS

MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	0.5 A
V_{RRM}	30 V
V_F (max)	0.33 V

SOD-123

FEATURES AND BENEFITS

- VERY SMALL CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- EXTREMELY FAST SWITCHING

DESCRIPTION

Single Schottky rectifier suited for switch mode power supplies and high frequency DC to DC converters.

Packaged in SOD-123, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications. Due to the small size of the package this device fits GSM and PCMCIA requirements.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		30	V
$I_{F(RMS)}$	RMS forward current		2	A
$I_{F(AV)}$	Average forward current δ=0.5	Ta=55°C	0.5	A
I_{FSM}	Surge non repetitive forward current	tp=10ms sinusoidal	5.5	A
dV/dt	Critical rate of rise of reverse voltage		10000	V/µs
T_{stg}	Storage temperature range		- 65 to + 125	°C
Tj	Maximum operating junction temperature *		125	°C
TL	Maximum temperature for soldering during 10s		260	°C

* : $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ thermal runaway condition for a diode on its own heatsink

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THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
$R_{th\ (j-a)}$	Junction to ambient	340 *	°C/W

(*) Copper area on PCB S = 2.5mm²

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Value STPS0530Z typ.	Value STPS0530Z max.	Unit
I_R *	Reverse leakage current	Tj = 25°C	V_R = 15 V		12	µA
		Tj = 125°C		3	5	mA
		Tj = 25°C	$V_R = V_{RRM}$		130	µA
		Tj = 125°C		9	21	mA
V_F **	Forward voltage drop	Tj = 25°C	I_F = 0.1 A		0.375	V
		Tj = 125°C		0.20	0.22	
		Tj = 25°C	I_F = 0.5 A		0.43	
		Tj=125°C		0.31	0.33	

Pulse test : * tp = 5 ms, δ < 2%
** tp = 380 µs, δ < 2%

To evaluate the maximum conduction losses use the following equation :
$P = 0.23 \times I_{F(AV)} + 0.18 \times I_{F}^{2}{}_{(RMS)}$

Fig. 1: Conduction losses versus average current.

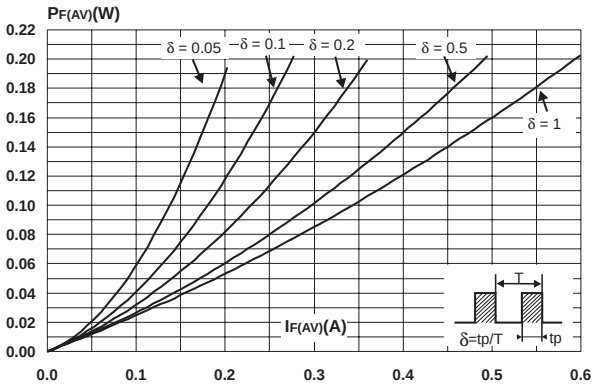


Fig. 2: Average forward current versus ambient temperature (δ = 0.5)

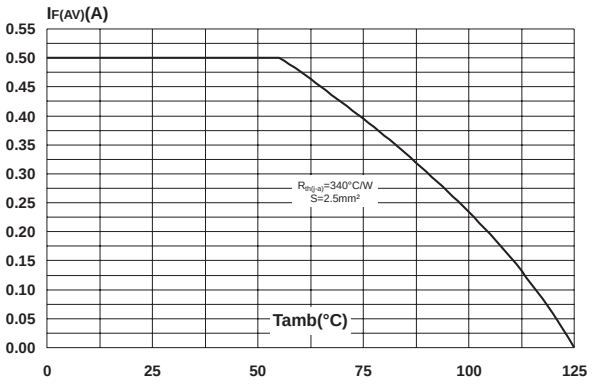


Fig. 3: Non repetitive surge peak forward current versus overload duration (maximum values).

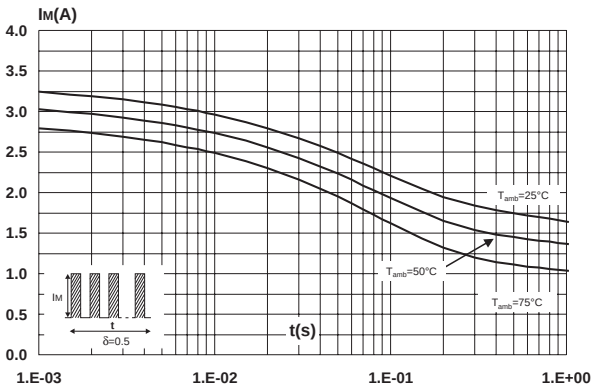


Fig. 4: Relative variation of thermal impedance junction to ambient versus pulse duration.

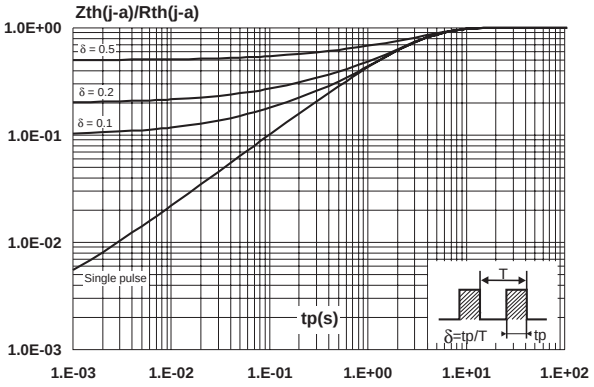


Fig. 5: Reverse leakage current versus reverse voltage applied (typical values).

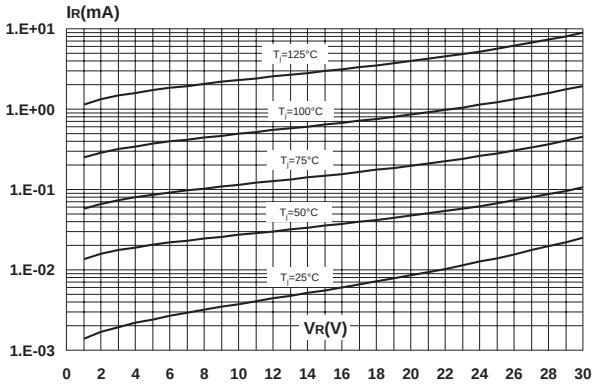


Fig. 6: Reverse leakage current versus junction temperature (typical values).

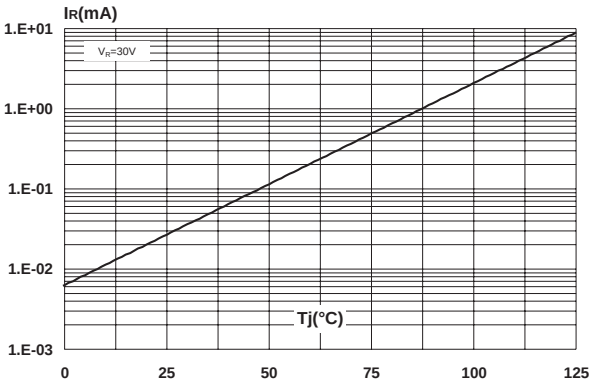


Fig. 7: Junction capacitance versus reverse voltage applied (typical values).

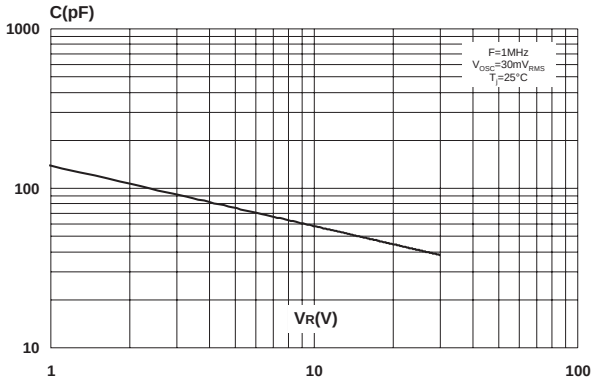


Fig. 8: Forward voltage drop versus forward current.

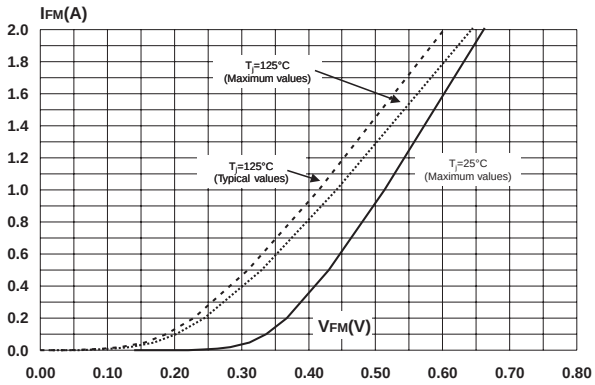
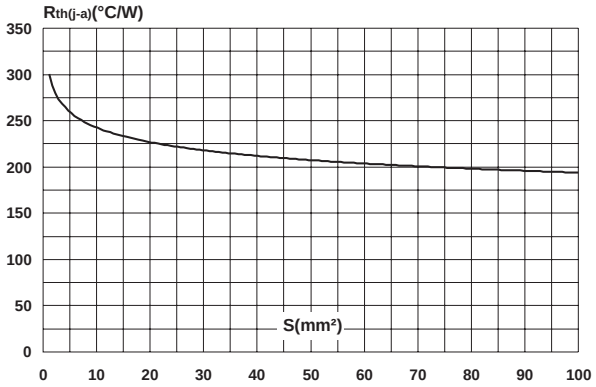
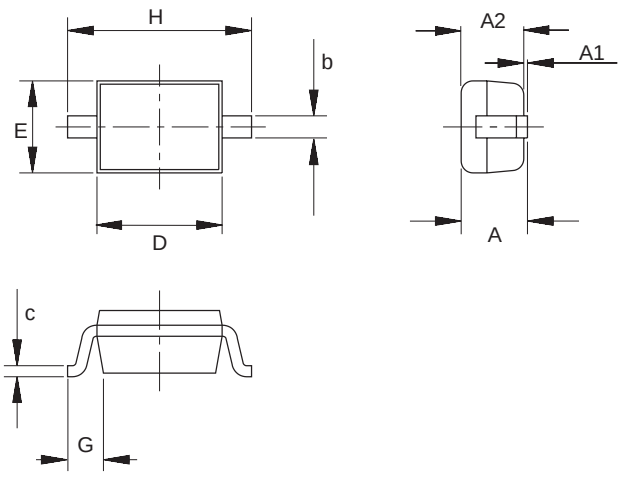


Fig. 9: Thermal resistance junction to ambient versus copper surface under each lead (epoxy printed board FR4, Cu=35µm, typical values).



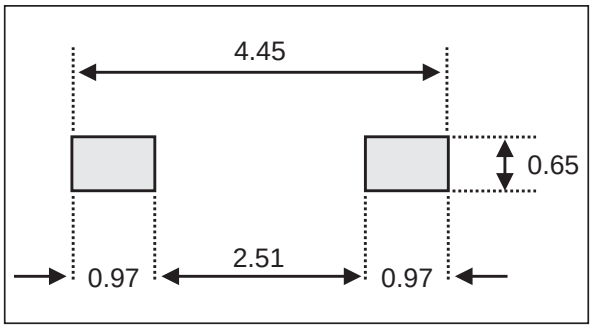
PACKAGE MECHANICAL DATA

SOD-123



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		1.45		0.057
A1	0	0.1	0	0.004
A2	0.85	1.35	0.033	0.053
b	0.55 Typ.		0.022 Typ.	
c	0.15 Typ.		0.039 Typ.	
D	2.55	2.85	0.1	0.112
E	1.4	1.7	0.055	0.067
G	0.25		0.01	
H	3.55	3.95	0.14	0.156

FOOTPRINT (in millimeters)



MARKING

Type	Marking	Package	Weight	Base qty	Delivery mode
STPS0530Z	Z53	SOD-123	0.01g.	3000	Tape & reel

- Epoxy meets UL94, V0.
- Band indicates cathode.

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